

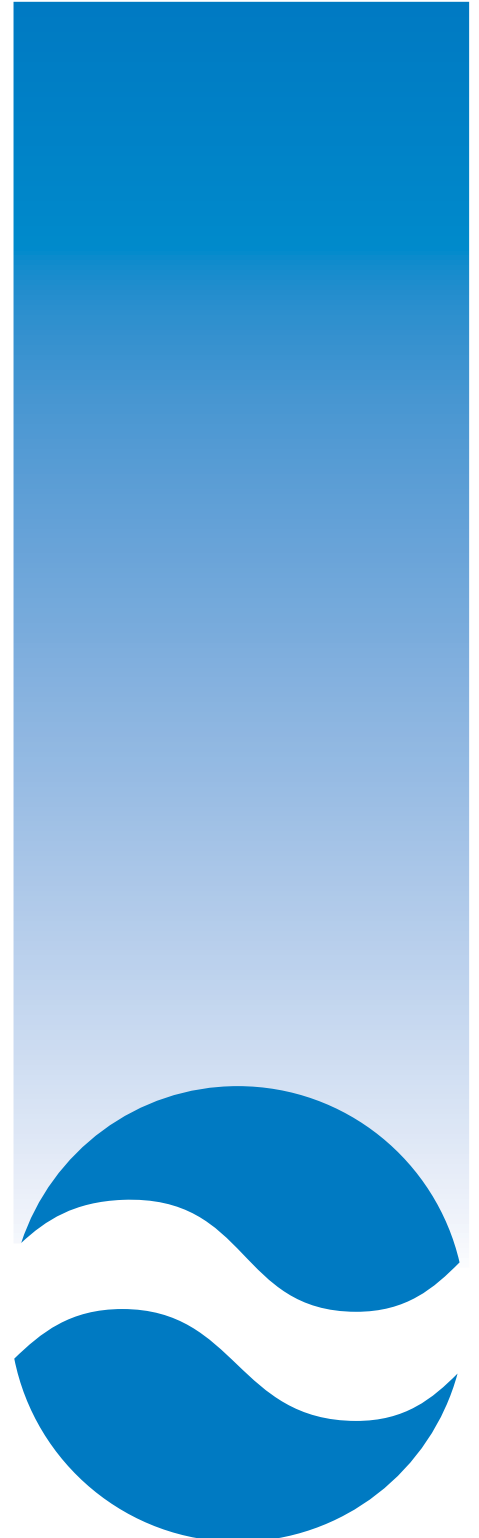
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February 2012**

JOINT INDUSTRY STANDARD

Requirements for Solder Pastes



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- Focus on end product performance
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IPC-J-STD-005B

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Developed by the 5-24B Task Group of the Assembly and Joining General Committee 5-20 of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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